

CMH08A

Switching Mode Power Supply Applications

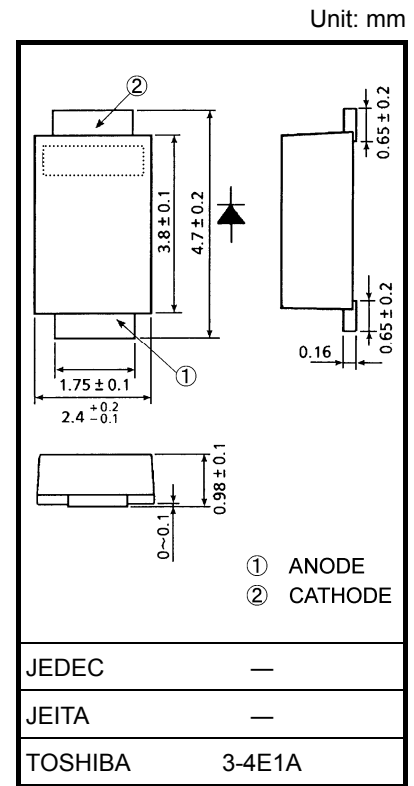
- Repetitive peak reverse voltage: $V_{RRM} = 400\text{ V}$
- Average forward current: $I_F (AV) = 2.0\text{ A}$
- Low forward voltage: $V_{FM} = 1.8\text{ V (Max.)}$
- Very Fast Reverse-Recovery Time: $trr = 35\text{ ns (Max.)}$
- Suitable for compact assembly due to small surface-mount package "M-FLAT™" (Toshiba package name)

Absolute Maximum Ratings ($T_a = 25^\circ\text{C}$)

Characteristics	Symbol	Rating	Unit
Repetitive peak reverse voltage	V_{RRM}	400	V
Average forward current	$I_F (AV)$	2.0 (Note 1)	A
Peak one cycle surge forward current (non-repetitive)	I_{FSM}	20 (50 Hz)	A
Junction temperature	T_j	-40~150	$^\circ\text{C}$
Storage temperature range	T_{stg}	-40~150	$^\circ\text{C}$

Note 1: $T_l = 99^\circ\text{C}$ Device mounted on a ceramic board
 board size: 50 mm × 50 mm
 soldering land: 2 mm × 2 mm
 board thickness: 0.64t

Note 2: Using continuously under heavy loads (e.g. the application of high temperature/current/voltage and the significant change in temperature, etc.) may cause this product to decrease in the reliability significantly even if the operating conditions (i.e. operating temperature/current/voltage, etc.) are within the absolute maximum ratings. Please design the appropriate reliability upon reviewing the Toshiba Semiconductor Reliability Handbook ("Handling Precautions"/Derating Concept and Methods) and individual reliability data (i.e. reliability test report and estimated failure rate, etc).



Weight: 0.023 g (typ.)

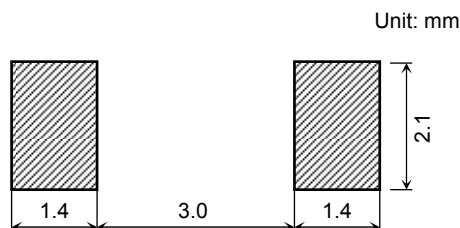
Electrical Characteristics ($T_a = 25^\circ\text{C}$)

Characteristics	Symbol	Test Condition	Min	Typ.	Max	Unit
Peak forward voltage	$V_{FM} (1)$	$I_{FM} = 0.1\text{ A}$ (pulse test)	—	0.88	—	V
	$V_{FM} (2)$	$I_{FM} = 1.0\text{ A}$ (pulse test)	—	1.3	—	
	$V_{FM} (3)$	$I_{FM} = 2.0\text{ A}$ (pulse test)	—	1.6	1.8	
Peak repetitive reverse current	I_{RRM}	$V_{RRM} = 400\text{ V}$ (pulse test)	—	—	10	μA
Reverse recovery time	t_{rr}	$I_F = 1\text{ A}$, $di/dt = -30\text{ A}/\mu\text{s}$	—	—	35	ns
Forward recovery time	t_{fr}	$I_F = 1.0\text{ A}$	—	—	100	ns
Thermal resistance (junction to ambient)	$R_{th} (j-a)$	Device mounted on a ceramic board (board size: 50 mm × 50 mm) (soldering land: 2 mm × 2 mm) (board thickness: 0.64 t)	—	—	60	$^\circ\text{C}/\text{W}$
		Device mounted on a glass-epoxy board (board size: 50 mm × 50 mm) (soldering land: 6 mm × 6 mm) (board thickness: 1.6 t)	—	—	135	
		Device mounted on a glass-epoxy board (board size: 50 mm × 50 mm) (soldering land: 2.1 mm × 1.4 mm) (board thickness: 1.6 t)	—	—	210	
Thermal resistance (junction to lead)	$R_{th} (j-t)$	—	—	—	16	$^\circ\text{C}/\text{W}$

Marking

Type code	Product No.
H8	CMH08A

Standard Soldering Pad



Handling Precaution

The absolute maximum ratings mean the absolute maximum ratings, which are rated values and must not be exceeded during operation, even for an instant. The followings are the general derating method that we recommend when you design a circuit with a device.

VRRM: We recommend that the worst case voltage, including surge voltage, be no greater than 80% of the absolute maximum rating of VRRM for a DC circuit and be no greater than 50% of that of VRRM for an AC circuit.

VRRM has a temperature coefficient (0.1%/°C). Please consider this temperature coefficient when you design a device at low temperature.

IF(AV): We recommend that the worst case current be no greater than 80% of the absolute maximum rating of IF(AV).

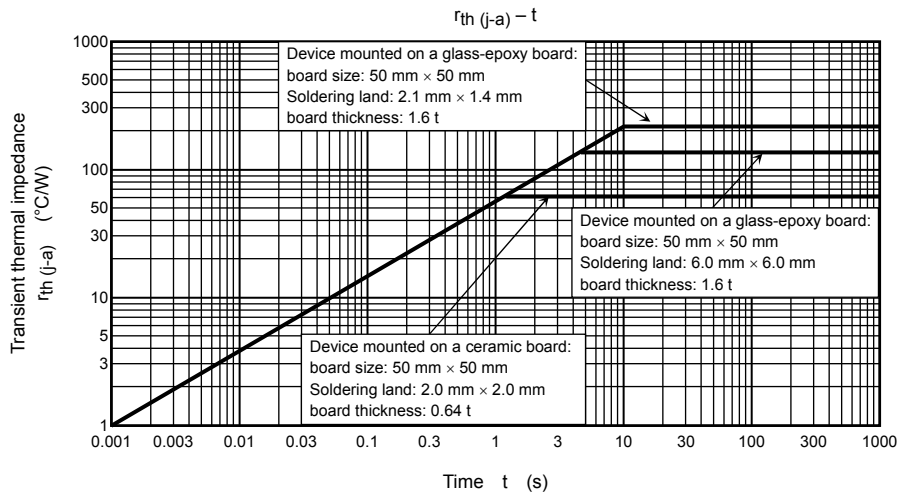
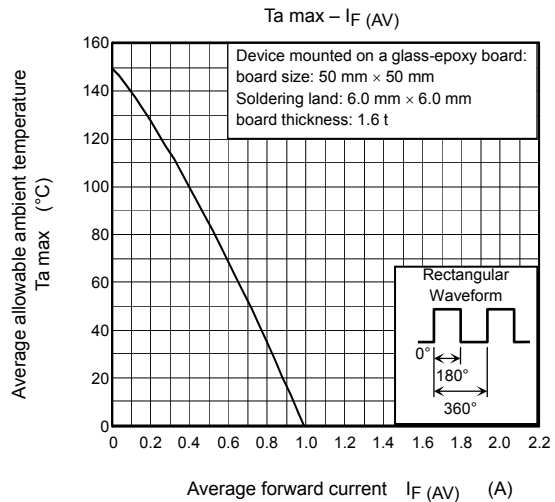
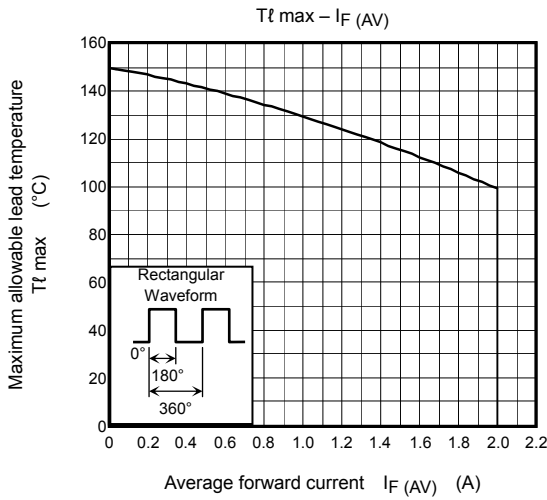
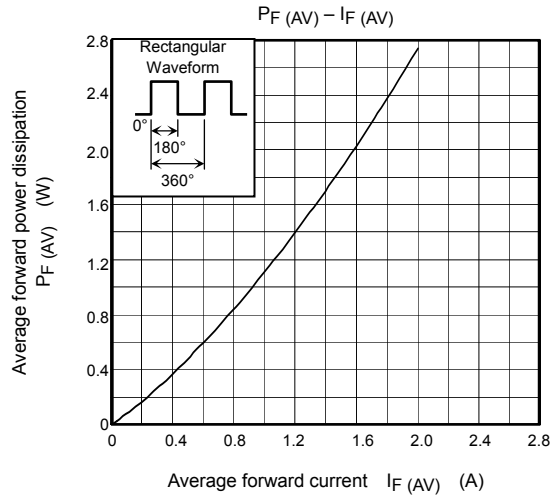
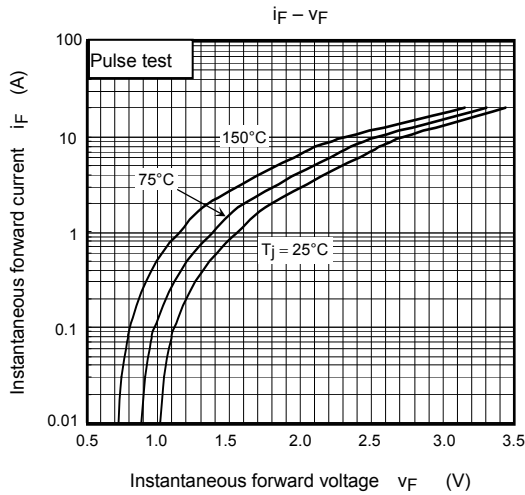
Please do the sufficient heat design. If you can't design a circuit with excellent heat radiation, please set a margin by using an allowable Tamax-IF (AV) curve.

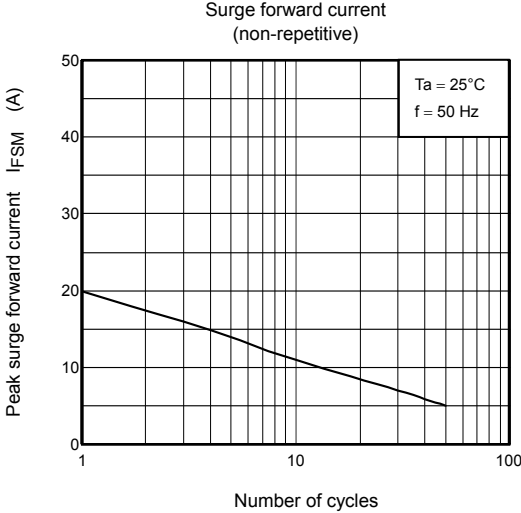
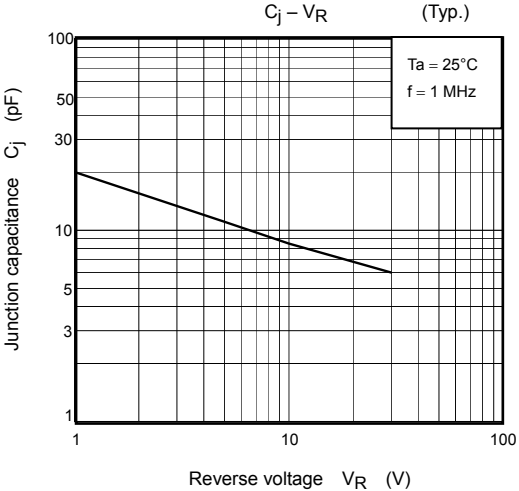
This rating specifies the non-repetitive peak current in one cycle of a 50-Hz sine wave, condition angle 180°. Therefore, this is only applied for an abnormal operation, which seldom occurs during device's lifespan.

We recommend that a device be used Tj of below 120°C under the worst load and heat radiation conditions.

Thermal resistance between junction and ambient fluctuates depending on device's mounting condition. When using a device, please design a circuit board and a soldering land size to match the appropriate thermal resistance value.

Please refer to Rectifier databook for further information.





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